

Title (en)  
LAMINATE FOR MULTI-LAYER PRINTED CIRCUIT

Title (de)  
LAMINAT FÜR MEHRLAGEN-LEITERPLATTE

Title (fr)  
STRATIFIE POUR CIRCUIT IMPRIME MULTICOUCHE

Publication  
**EP 1166353 A4 20030604 (EN)**

Application  
**EP 99964034 A 19991201**

Priority  
• US 9928442 W 19991201  
• US 26695199 A 19990312

Abstract (en)  
[origin: WO0055908A1] A laminate for use as a surface laminate in a multi-layer printed circuit board. The laminate is comprised of a film substrate (12) formed of a first polymeric material. At least one layer of a flash material (14) is applied to a first side of the film substrate. At least one layer of copper (16) is disposed on the layer of flash material. An adhesive layer (18) formed of a second polymer material has a first surface that is attached to a second side of the film substrate.

IPC 1-7  
**H05K 3/46**; H01L 23/053; H01L 23/12; H01L 23/10; H01L 23/34

IPC 8 full level  
**B32B 15/08** (2006.01); **B32B 15/088** (2006.01); **H05K 1/03** (2006.01); **H05K 3/24** (2006.01); **H05K 3/46** (2006.01); **H05K 3/18** (2006.01); **H05K 3/38** (2006.01)

CPC (source: EP KR US)  
**H05K 3/46** (2013.01 - KR); **H05K 3/4652** (2013.01 - EP US); **H05K 3/4655** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US); **H05K 3/181** (2013.01 - EP US); **H05K 3/386** (2013.01 - EP US); **H05K 3/387** (2013.01 - EP US); **H05K 3/388** (2013.01 - EP US); **H05K 2201/0195** (2013.01 - EP US); **H05K 2201/0344** (2013.01 - EP US); **Y10T 428/12542** (2015.01 - EP US); **Y10T 428/12556** (2015.01 - EP US); **Y10T 428/1291** (2015.01 - EP US); **Y10T 428/12917** (2015.01 - EP US); **Y10T 428/24917** (2015.01 - EP US); **Y10T 428/28** (2015.01 - EP US); **Y10T 428/31681** (2015.04 - EP US)

Citation (search report)  
• [XY] US 5284548 A 19940208 - CAREY DAVID H [US], et al  
• [Y] EP 0115460 A2 19840808 - INF MILIT SPATIALE AERONAUT [FR]  
• [A] US 5436062 A 19950725 - SCHMIDT WALTER [CH], et al  
• See references of WO 0055908A1

Designated contracting state (EPC)  
DE FR GB IT

DOCDB simple family (publication)  
**WO 0055908 A1 20000921**; CA 2360323 A1 20000921; CN 1163958 C 20040825; CN 1333920 A 20020130; EP 1166353 A1 20020102; EP 1166353 A4 20030604; JP 2002539645 A 20021119; KR 20010105375 A 20011128; US 6268070 B1 20010731

DOCDB simple family (application)  
**US 9928442 W 19991201**; CA 2360323 A 19991201; CN 99815800 A 19991201; EP 99964034 A 19991201; JP 2000606052 A 19991201; KR 20017011274 A 20010904; US 26695199 A 19990312